

Materials for Micro- and Opto-Electronics

U.S. microelectronics and related industries are in fierce international competition to design and produce smaller, lighter, faster, more functional, and more reliable electronics products more quickly and economically than ever before. At the same time, there has been a revolution in recent years in new materials used in all aspects of microelectronics fabrication.

Since 1994, the NIST Materials Science and Engineering Laboratory (MSEL) has worked closely with the U.S. semiconductor, component, packaging, and assembly industries. These efforts led to the development of an interdivisional MSEL program committed to addressing industry's most pressing materials measurement and standards issues central to the development and utilization of advanced materials and material processes. The vision that accompanies this program — to be the key resource within the Federal Government for materials metrology development for commercial microelectronics manufacturing — may be realized through the following objectives:

- Develop and deliver standard measurements and data;
- Develop and apply *in situ* measurements on materials and material assemblies having micrometer- and submicrometer-scale dimensions;
- Quantify and document the divergence of material properties from their bulk values as dimensions are reduced and interfaces contribute strongly to properties;
- Develop models of small, complex structures to substitute for or provide guidance for experimental measurement techniques; and
- Develop fundamental understanding of materials needed in future micro- and opto-electronics.

With these objectives in mind, the program presently consists of projects led by the Metallurgy, Polymers, Materials Reliability, and Ceramics Divisions that examine and inform industry on key materials-related issues. These projects are conducted in concert with partners from industrial consortia, individual companies, academia, and other government agencies. The program is strongly coupled with other microelectronics programs within government and industry, including the National Semiconductor Metrology Program (NSMP) at NIST. Materials metrology needs are also identified through industry groups and roadmaps, including the International Technology Roadmap for Semiconductors (ITRS), the IPC Lead-free Solder Roadmap, the National

Electronics Manufacturing Initiative (NEMI) Roadmap, the Optoelectronics Industry Development Association (OIDA) roadmaps, and the National [Magnetic Data] Storage Industry Consortium (NSIC).

Although there is increasing integration within various branches of microelectronics and optoelectronics, the field can be considered in three main areas. The first, microelectronics, includes needs ranging from integrated circuit fabrication to component packaging to final assembly. MSEL programs address materials metrology needs in each of these areas, including lithographic polymers and electrodeposition of interconnects, electrical, mechanical, and physical property measurement of dielectrics (interlevel, packaging, and wireless applications), and packaging and assembly processes (lead-free solders, solder interconnect design, thermal stress analysis, and co-fired ceramics).

The second major area is optoelectronics, which includes work which often crosses over into electronic and wireless applications. Projects currently address residual stress measurement in optoelectronic films, optical and structural characterization of wide bandgap semiconductors, and standards development for III–V compound semiconductors. Cross-laboratory collaborations with EEEL figure prominently in this work.

The third area is magnetic data storage, where the market potential is vast and growing and the technical challenges extreme. NSIC plans to demonstrate a recording density of 1 terabit per square inch — 40 times today's level — by 2006. To reach these goals, new materials are needed that have smaller grain structures, can be produced as thin films, and can be deposited uniformly and economically. New lubricants are needed to prevent wear as spacing between the disk and head becomes smaller than the mean free path of air molecules. Some measurements require calibration of magnetometers using certified magnetic standards in several different shapes and magnetic strengths, and with a wide range in magnetic character. MSEL is working with the magnetic recording industry to develop measurement tools, modeling software, and standards to help achieve these goals, with MSEL, the Electronics and Electrical Engineering Laboratory, the Physics Laboratory, the Information Technology Laboratory, and the Manufacturing Engineering Laboratory working as partners in this effort.

Contact: Martin Green